

Abstract

The laminate of the invention has a semiconductor substrate, a support substrate, a release layer disposed so as to come into contact with the semiconductor substrate, and an adhesive layer disposed between the support substrate and the release layer, characterized in that the release layer is a film formed from a releasing agent composition containing a polyorganosiloxane component essentially containing polydimethylsiloxane; the polyorganosiloxane component has a viscosity of 5.50×10^3 Pa·s to 0.75×10^3 Pa·s, as measured at 25°C; and the film has a thickness of 0.01 μm to 4.90 μm .

[No figure]